IEEE MMSP 2022 will be held on September 26–28, 2022 in Shanghai, China. It is 24th in the series, organized by the Multimedia Signal Processing Technical Committee of the IEEE Signal Processing Society (SPS), with the aim to bring together researchers and practitioners from academia and industry, passionate about multimedia signal processing, to share their knowledge, exchange ideas, explore future research directions and network.

Prospective authors are invited to submit regular and special session papers (full length, 4-6 pages), demo papers (1 page) and grand challenge contributions. Conference content will be submitted for inclusion into IEEE Xplore as well as other Abstracting and Indexing (A&I) databases. Papers are solicited in, but not limited to, the following areas:

- Image/Video/Speech Signal Processing
- Audio/Text/New Sensors Signal Processing
- Multimedia Interaction
- Multimedia Content Analysis
- Multimedia Ethics and Privacy
- Multimedia Security and Forensics
- Multimedia Hardware and Software
- Multimedia for Human Networks
- Virtual Reality and Augmented Reality
- Human-Machine Interaction for Multimedia Applications
- Multimedia Big Data Analysis for Humanity
- Multimedia Database and Digital Libraries
- Multimedia Communications and Networking
- 3D Imaging, Visualization, Reconstruction and Animation

**TimeLine**

- Special Session/Grand Challenge Proposal Submission: 20 April 2022
- Regular and Special Session Paper Submission: 1 June 2022
- Notification of Paper Acceptance: 13 July 2022
- Demo Paper Submission: 3 August 2022

**General Chairs**
Xiaofan Wang, Shanghai University, China
Ivan Bajić, Simon Fraser University, Canada
Yonggang Wen, Nanyang Technological University, Singapore

**Technical Programme Chairs**
Maria Martini, Kingston University London, UK
Lingyu Duan, Peking University, China
Dan Zeng, Shanghai University, China

**Keynote Chairs**
Jenq-Neng Hwang, University of Washington, USA
Yugang Jiang, Fudan University, China

**Special Sessions Chairs**
Weiyao Lin, Shanghai Jiao Tong University, China
Zhu Li, University of Missouri, USA

**Sponsorship Chair**
Qi Tian, Huawei, China

**Demo/Industrial Chairs**
Wen-Huang Cheng, National Yang Ming Chiao Tung University
Jiaying Liu, Peking University, China

**Publicity Chairs**
Tao Mei, JD.COM, China
Yuming Fang, Jiangxi University of Finance and Economics, China
Shenghua Gao, ShanghaiTech University, China

**Finance Chairs**
Xiaoqiang Zhu, Shanghai University, China
Tao Peng, Shanghai University, China

**Publication Chairs**
Jiwen Lu, Tonghua University, China
Liqian Shen, Shanghai University, China

**International Liaison Chairs**
Ali C. Begen, Ozyegin University, Turkey
Xiao-Ping Zhang, Ryerson University, Canada

**Local Arrangements Chairs**
Junjie Zhang, Shanghai University, China
Zhichao Sheng, Shanghai University, China

**Awards Chair**
Jun Wu, Fudan University, China

**Registration Chair**
Hongwen Yu, Shanghai University, China

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